Special Issue

Advanced Manufacturing of Soft Materials

Message from the Guest Editor

Soft materials include polymers, foams, gels, porous and granular materials and biomaterials and have found application in a wide range of applications, from flexible electronics and regenerative medicine. This Special Issue of *Applied Sciences*, "Advanced Manufacturing of Soft Materials", is intended for a wide and interdisciplinary audience and covers recent advances in:

- Development of new manufacturing techniques and processing of soft materials;
- Innovative concepts in additive manufacturing;
- Formulation of functional and structured soft materials;
- Bio-inspired design and self-assembly methods;
- Integration of soft materials with coatings and rigid systems.

For further reading, please visit the ***Special Issue website.***

Guest Editor
Dr. David Cheneler
Department of Engineering, Lancaster University, Lancaster LA1 4YW, UK

Deadline for manuscript submissions

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Applied Sciences
Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland
Tel: +41 61 683 77 34
applsci@mdpi.com

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo
Dipartimento di Fisica, Politecnico di Milano, Piazza L. da Vinci 32,
20133 Milano, Italy

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